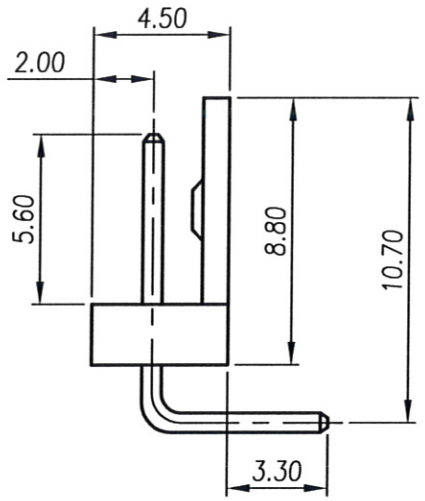
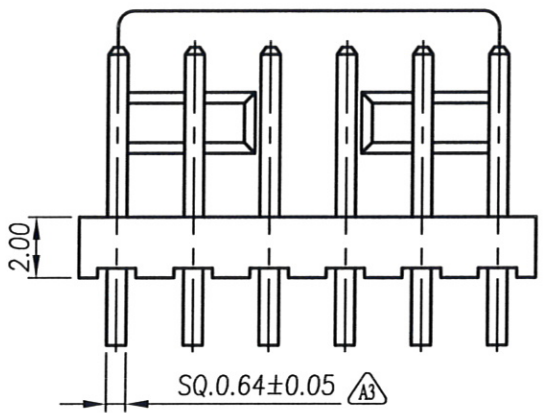
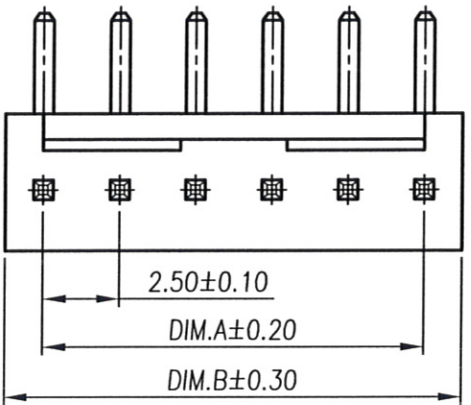


1 2 3 4 5 6 7 8

RoHS Compliant

REV	MODIFICATION	DATE	DRAW
A1	Release To ECN20130303	2013.03.12	Seven
A2	Release To ECN20140507	2014.05.13	Michelle
A3	Release To ECN20150610	2015.06.23	Michelle

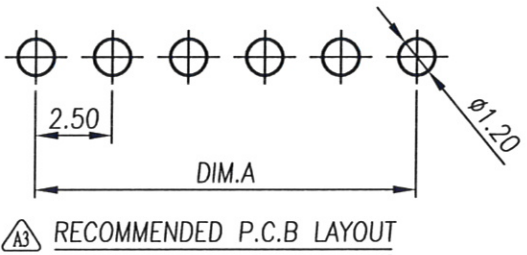


Specification
 1.Current Rating:2A AC/DC
 2.Voltage Rating:250V AC/DC
 3.Contact Resistance:20mΩ Max.
 4.Insulation Resistance:1000MΩ Min. At DC 500V
 5.Dielectric Withstanding Voltage:AC800V/Minute
 6.Operating Temperature:-25°C~+85°C


Material:
 1.Housing:High Temperature Thermoplastic UL94V-2
 2.Contact Pin:Copper Alloy SQ. Pin 0.64mm

Finish:
 1.Housing:Natural
 2.Contact Pin:Bright Tin Plated Over Nickel

Part No.: AD04701 XX 0 1 5 2
 No. Of Pin: A2 02~10
 Packing: 5:Bag
 Housing Material: 0:PA66 UL94V-2 Natural
 Plating: 1:Bright Tin Plated Over Nickel




PIN	DIM.A	DIM.B
02	2.50	5.10
03	5.00	7.60
04	7.50	10.10
05	10.00	12.60
06	12.50	15.10
07	15.00	17.60
08	17.50	20.10
09	20.00	22.60
10	22.50	25.10



金上達科技股份有限公司

GOLDENSUND TECHNOLOGY CO.,LTD

TOLERANCE UNLESS OTHERWISE SPECIFIED		PROJ. 	TITLE: Wire To Board Wafer 2.50mm 90° DIP Single Row		
.x± 0.35	x.*± 2'	APR. C.F.Liao 20150623	PART NO. AD04701XX0152	DWG NO. AD04701XX0152	
.xx± 0.25	.x.*± 1'	CHK. Abel 20150623	UNITS: mm	CUSTOMER DRAWING	
.xxx± 0.15	.xx.*± 0.5'	DRA. Michelle 20150623	SIZE: A4	SCALE: 4:1	SHEET 1 / 1
			REV: A3	V	

1 2 3 4 5 6 7 8